



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.: 10/068755 Confirmation No.: 9286
Applicant: DENT, et al.
Filed: 16/MAY/2002
TC/A.U.: 2811
Examiner: Im, Junghwa M
Docket No.: DC4968 NP 1
Customer No.: 00137
Date: 25 January 2005
For: Semiconductor Package and Method of Preparing Same

Fee Sheet

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

APPEAL BRIEF

Real Party in Interest

The real party in interest in this appeal is Dow Corning Corporation, the assignee of the above application.

Related Appeals and Interferences

Appellants are not aware of any related appeals or interferences that will directly affect or be directly affected by or have a bearing on the Board's decision in the pending appeal.

Status of Claims

Claims 1-29 were originally filed in this application. Claims 15-19 and 23-25 were amended and claims 20-22 were canceled in a preliminary amendment dated 22 April 2003. Claims 30-32 were added by an amendment dated 11 August 2003. Claims 1 and 14 were amended by an

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